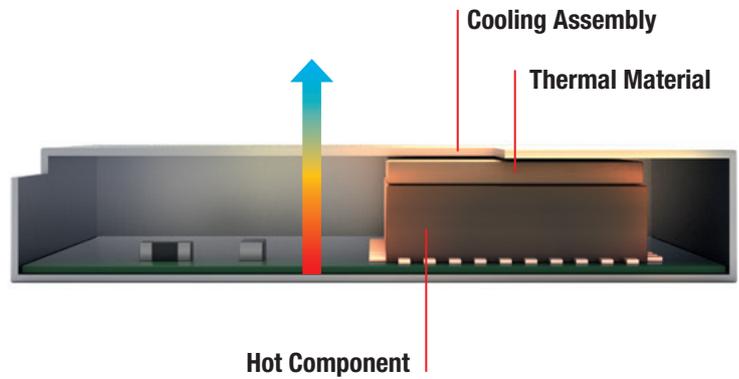


# Thermal Management Solutions

## Control over the Component Heat

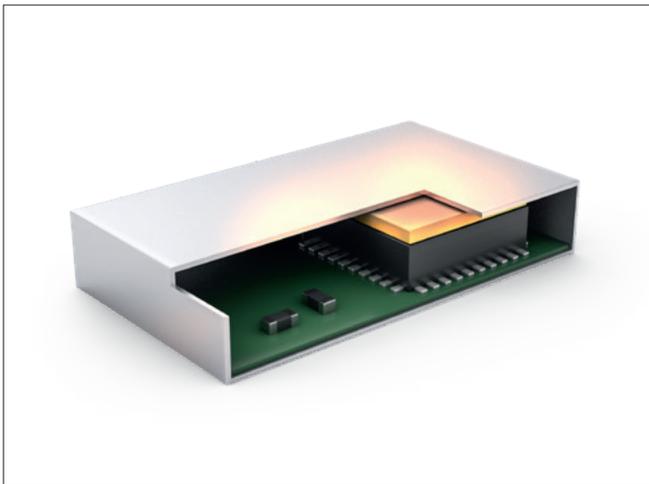
Thermal Management describes all the methods used to take care of all the excess heat that electronic devices and components generate. It is a field of utmost importance in order to guarantee reliability of electronic devices and components, develop robust devices and reduce e-waste.

- Provide a path for the heat energy
- Spreading the heat over a larger dissipation area
- Avoiding the overheating of components



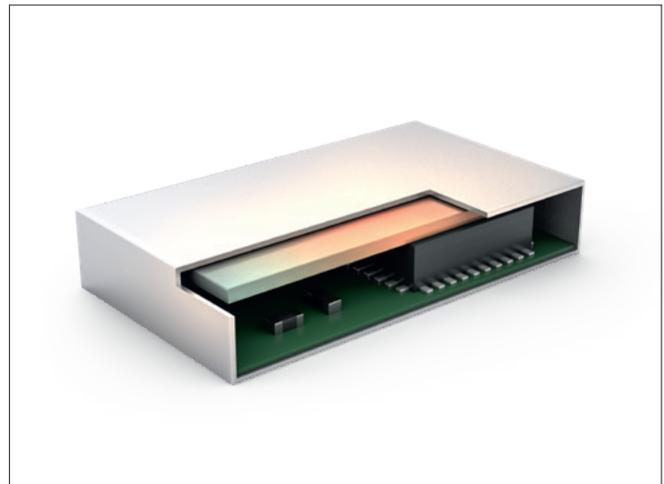
## Thermal Management Solutions Categories

### Gap Fillers



Gap Fillers remove the air between a component and a cooling assembly, from small to large gaps.

### Heat Spreaders



Heat Spreaders distribute heat energy in a horizontal axis. This enables the use of large surfaces for heat dissipations as well as use cooling assemblies larger than the surface of the hot component for enhanced cooling.



See the complete portfolio:  
[www.we-online.com/thermalmanagement](http://www.we-online.com/thermalmanagement)

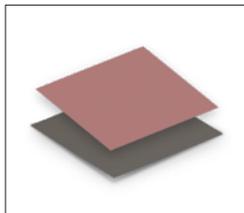
## Thermal Management Portfolio

Depending on the requirements of the application, we have a solution for you: whether the need to fill a small or large gap, one that enables the mounting of a cooling assembly without the need of additional mechanical fixing or the need of a heat spreading product.



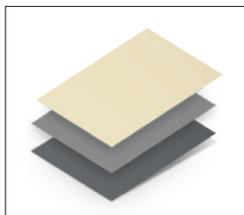
**WE-TGF**  
Silicone Gap Filler Pad  
K: 1–10 W/mK  
Thickness: 0.5–18 mm

WE-TGF is a silicone elastomer gap filler pad, designed to fill a gap between one or multiple electronic components and a cooling assembly, such as heatsink, a cooling plate or a metal housing.



**WE-TINS**  
Thermally Conductive Insulator  
K: 1.6–3.5 W/mK  
Thickness: 0.23 mm

WE-TINS is a thin silicone pad designed to electrically insulate electronic components and cooling assemblies while allowing the flow of heat.



**WE-PCM**  
Phase Changing Material  
K: 1.6–5 W/mK  
Thickness: 0.2 mm

WE-PCM is a phase changing material. These materials are known for remaining solid at room temperature and changing into a flowing state with increasing temperature to ensure the best thermal interface.



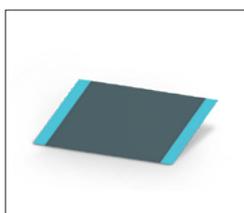
**WE-TTT**  
Thermal Transfer Tape  
K: 1 W/mK  
Thickness: 0.2 mm

WE-TTT is a double sided tape designed to provide a thermal interface that at the same time allows mechanical fixing in both contact surfaces without the need of additional screws or clips.



**WE-TGFG**  
Graphite Foam Gasket  
K: 400 W/mK  
Thickness: 1.5–25 mm

WE-TGFG is a synthetic graphite layer wrapped around a core of foam. This enables the use of a highly conductive heat spreader to fill vertical gaps and provide a silicone-free alternative to the WE-TGF.



**WE-TGS**  
Graphite Sheet  
K: 1800 W/mK  
Thickness: 0.03 mm

WE-TGS is a synthetic graphite heat spreader. This implies that most of the thermal conductivity provided by the material occurs at the horizontal or XY axis.